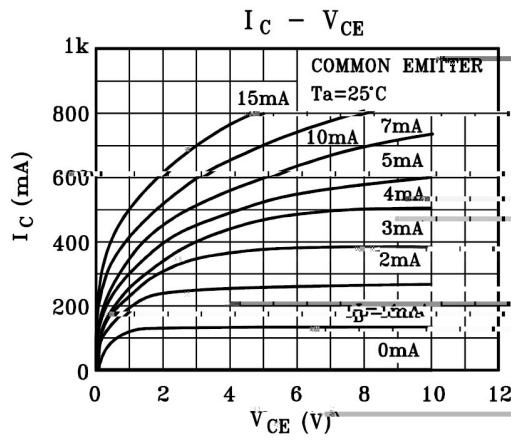
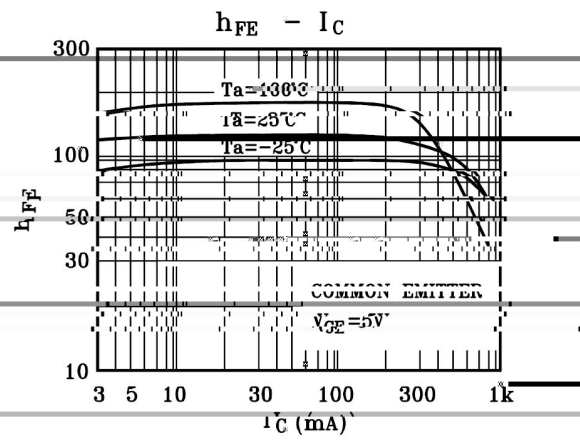
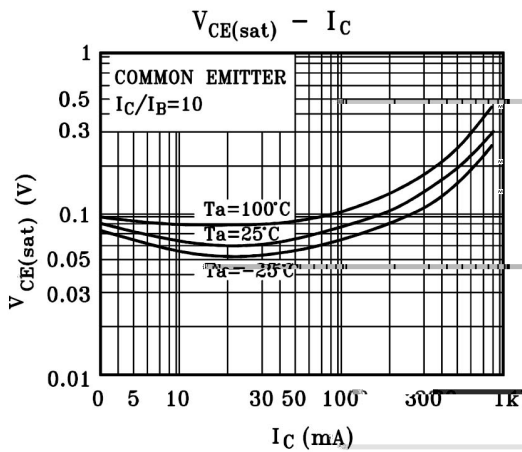
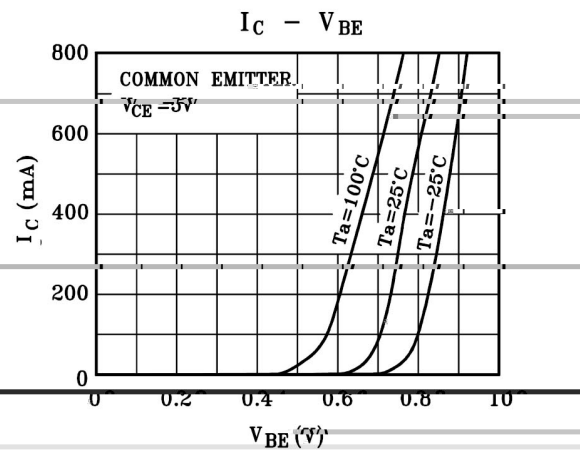
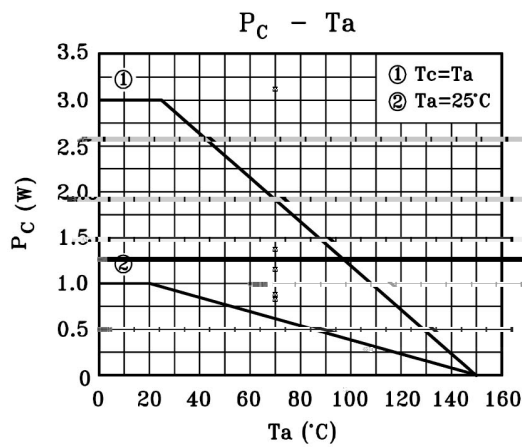
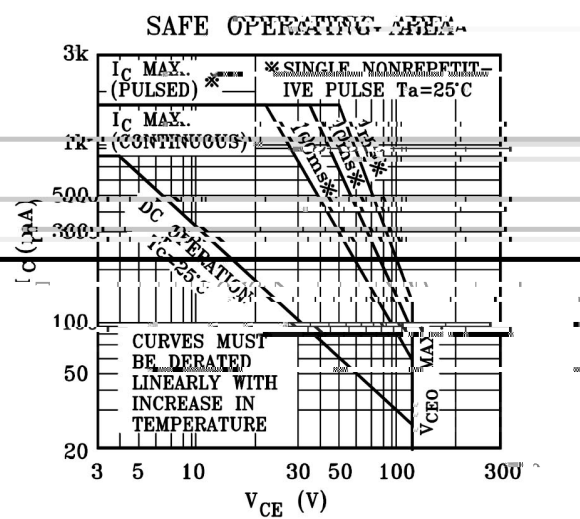


Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	120	V
Collector to Emitter Voltage	V_{CEO}	120	V
Emitter to Base Voltage	V_{EBO}	5.0	V
Collector Current - Continuous	I_C	800	mA
Emitter Current - Continuous	I_E	-800	mA
Collector Power Dissipation	P_C	1.0	W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=10mA$ $I_B=0$	120			V
Collector to Base Breakdown Voltage	V_{EBO}	$I_E=1mA$ $I_C=0$	5.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=120V$ $I_E=0$			0.1	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=5V$ $I_C=0$			0.1	μA

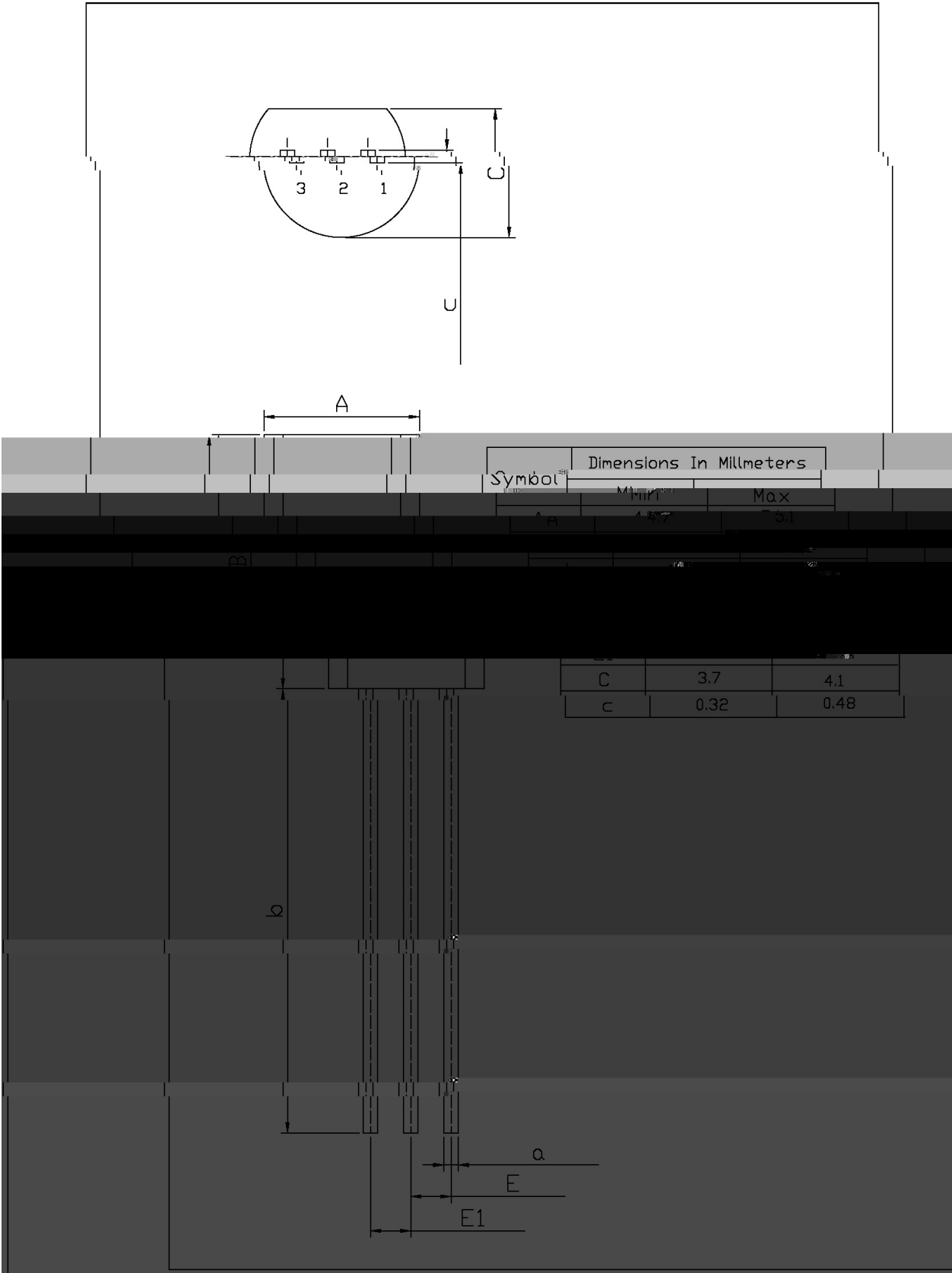
/ Electrical Characteristic Curve



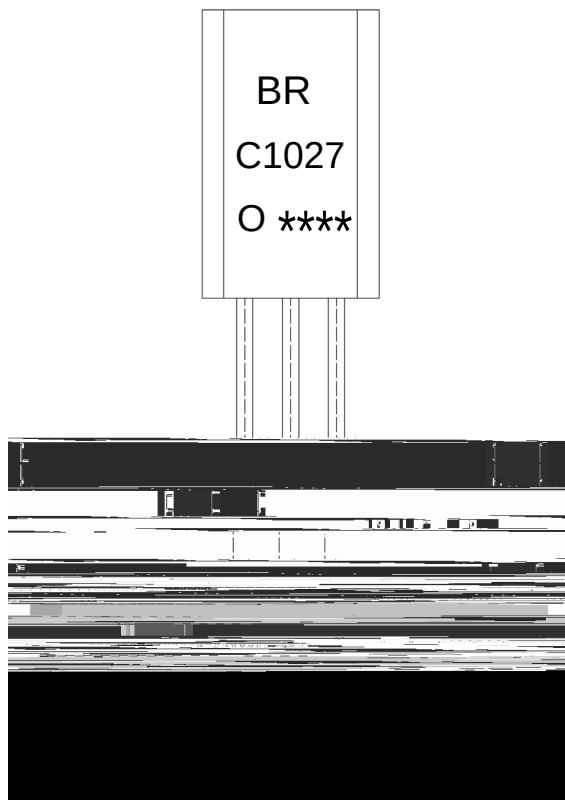
/ Package Dimensions

T0-92LM

Unit: mm



/ Marking Instructions



б " X

EU: Խ Յ Մ Ո

F435: X Խ Յ Մ Ո

R: Խ k_{IH}՝ Ե Ո

---- X Խ ի Բ ղ Մ Ո ի Զ ի Բ ղ Մ Ս Ր

Note:

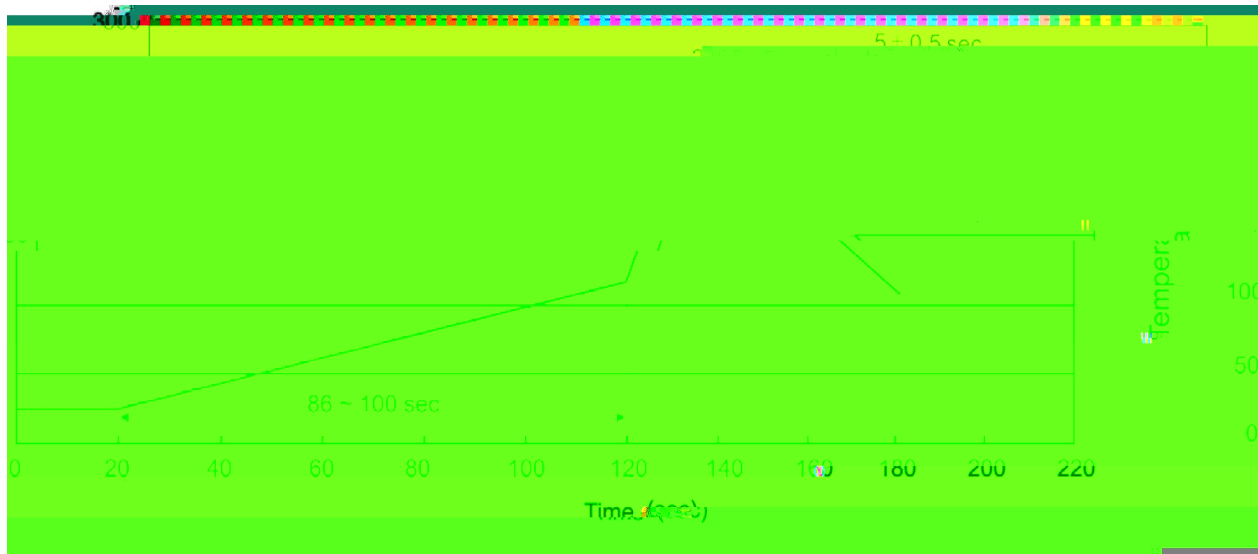
BR: Company Code.

C1027: Product Type.

O: h_{FE} Classifications Symbol

****: Lot No. Code,code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



注意

1. 预加热: 25~150 °C, Time: 60~90sec;
2. 峰值温度: 255 °C, Time: 5 ± 0.5sec;
3. 冷却速度: 2~10 °C/sec.

Note:

1. Preheating: 25~150 °C, Time: 60~90sec.
2. Peak Temp.: 255 °C, Duration: 5 ± 0.5sec.
3. Cooling Speed: 2~10 °C/sec.

/ Resistance to Soldering Heat Test Conditions

测试条件: 270 °C, Time: 10 ± 1 sec. Temp.: 270 °C Time: 10 ± 1 sec

/ Packaging SPEC.

散装 / BULK

Package Type	Units					Dimension (unit mm3)		
	Units/Bag	Bags/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Bag	Inner Box	Outer Box
TO-92LM	1,000	8	8,000	5	40,000	135×190	237×172×102	560×245×195

Ammo / AMMO

Package Type	Units					Dimension (unit mm3)	
	Units/tape	Tape/Inner Box	Rows/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Inner Box	Outer Box
TO-92LM	2,500	1	100	10	25,000	328×230×42	480×346×235 547×407×268

/ Notices